

MOS POWER 4
IGBT T-39-31

SML40G100AN 1000V 40A

N - CHANNEL ENHANCEMENT MODE HIGH VOLTAGE POWER INSULATED GATE BIPOLAR TRANSISTOR

MAXIMUM RATINGS

All Ratings: $T_C = 25^\circ\text{C}$ unless otherwise specified.

Symbol	Parameter	SML40G100AN	UNIT
V_{CES}	Collector-Emitter Voltage	1000	Volts
V_{GE}	Gate-Emitter Voltage	± 20	
I_{C1}	Continuous Collector Current	40	Amps
I_{C2}	Continuous Collector Current @ $T_C = 100^\circ\text{C}$	21	
I_{CM}	Pulsed Collector Current ^①	80	
I_{LM}	Clamped Inductive Load Current @ $T_J = +125^\circ\text{C}$ ^②	42	
P_D	Total Power Dissipation	145	Watts
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to 150	$^\circ\text{C}$
T_L	Max. Lead Temp. for Soldering Conditions: 0.063" from Case for 10 Sec.	300	

STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
BV_{CES}	Collector-Emitter Breakdown Voltage ($V_{GE} = 0V, I_C = 250\mu\text{A}$)	1000			Volts
RBV_{CES}	Reverse Collector-Emitter Breakdown Voltage ($V_{GE} = 0V, I_C = -1.0A$)	-15	-25		
$V_{GE(TH)}$	Gate Threshold Voltage ($V_{CE} = V_{GE}, I_C = 1.0mA$)	2.5		5	
$V_{CE(ON)}$	Collector-Emitter On Voltage ($V_{GE} = 15V, I_C = I_{C2}$)			3.3	
I_{CES}	Collector Cut-off Current ($V_{CE} = V_{CES}, V_{GE} = 0V$)			500	μA
	Collector Cut-off Current ($V_{CE} = 0.8 V_{CES}, V_{GE} = 0V, T_C = 125^\circ\text{C}$)			1.0	mA
I_{GES}	Gate-Emitter Leakage Current ($V_{GE} = \pm 20V, V_{CE} = 0V$)			± 100	nA

THERMAL CHARACTERISTICS

Symbol	Characteristic	MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction to Case			0.86	$^\circ\text{C/W}$
$R_{\theta JA}$	Junction to Ambient			30	

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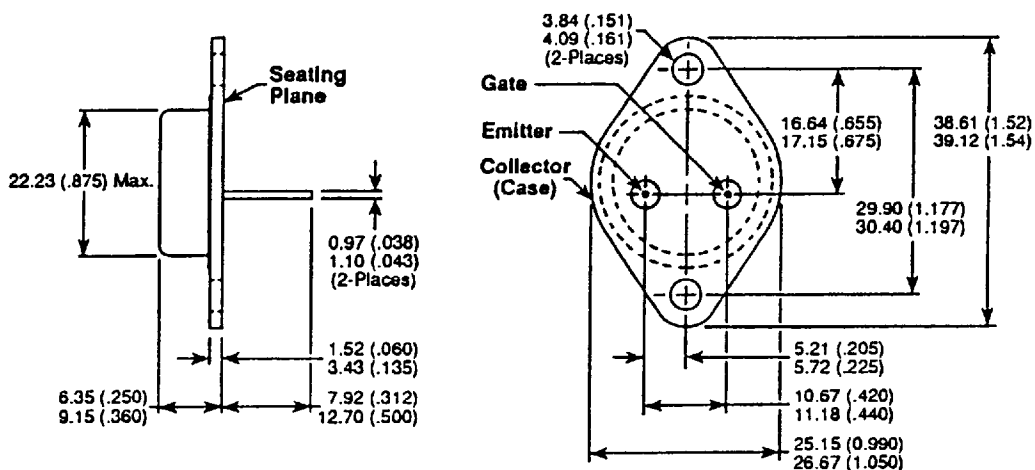
DYNAMIC CHARACTERISTICS

SML40G100AN

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
C_{ies}	Input Capacitance	$V_{GE} = 0V$ $V_{CE} = 25V$ $f = 1 \text{ MHz}$			2235	pF
C_{oes}	Output Capacitance				280	
C_{res}	Reverse Transfer Capacitance				95	
Q_g	Total Gate Charge ^③	$V_{GE} = 10V$ $V_{CC} = 0.5 V_{CES}$ $I_C = I_{C1}$		69	103	nC
Q_{ge}	Gate-Emitter Charge			9	13	
Q_{gc}	Gate-Collector ("Miller") Charge			41	61	
$t_{d(on)}$	Turn-on Delay Time (Resistive Switching)	$V_{GE} = 15V$ $V_{CC} = 0.5 V_{CES}$ $I_C = I_{C2}$ $R_G = 50\Omega$		75		ns
t_r	Rise Time (Resistive Switching)			200		
$t_{d(off)}$	Turn-off Delay Time (Resistive Switching)			600		
t_f	Fall Time (Resistive Switching)			600		
$t_{d(off)}$	Turn-off Delay Time (Inductive Switching)	$V_{CLAMP(Peak)} = 0.8V_{CES}$ $V_{GE} = 15V, I_C = I_{C2}$ $R_G = 50\Omega, T_J = 125^\circ C$		750		ns
t_f	Fall Time (Inductive Switching)			600		

- ① Repetitive Rating: Pulse width limited by maximum junction temperature.
 ② $V_{CLAMP} = 0.8V_{CES}$ Volts, $R_G = 50\Omega$.
 ③ See MIL-STD-750 Method 3471

TO-3 Package Outline (TO-204AE)



Dimensions in Millimeters and (Inches)

TYPICAL SOURCE-DRAIN DIODE FORWARD VOLTAGE

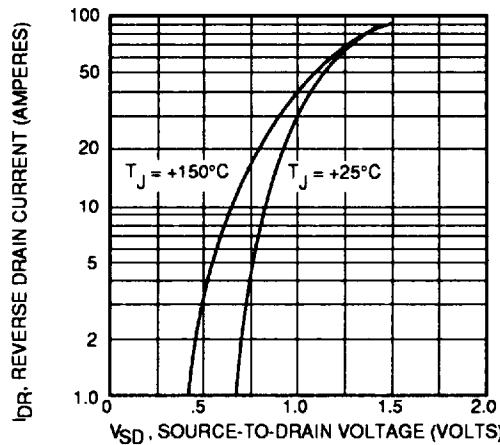
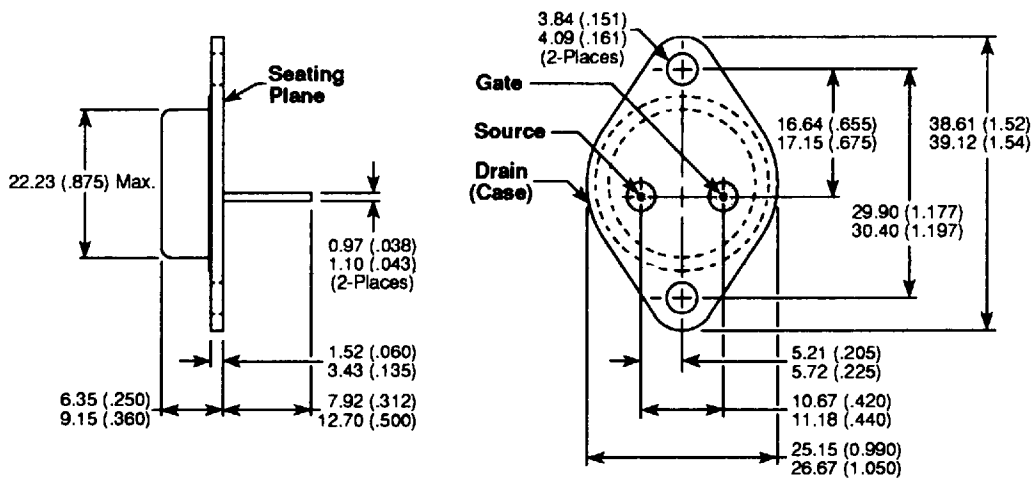


FIGURE 13, TYPICAL SOURCE-DRAIN DIODE FORWARD VOLTAGE

This curve shows the reverse drain current and source-drain forward voltage characteristics of the parasitic diode. The temperature coefficient (TC) of the diode can be derived by utilizing the following formula:

$$TC = \frac{V_{SD}(150^{\circ}C) - V_{SD}(25^{\circ}C)}{125^{\circ}C}$$

PACKAGE OUTLINE



Dimensions in Millimeters and (Inches)

This drawing gives all the mechanical drawings and dimensions for the package. This is a standard package and conforms to the present industry standards. For further information, contact the factory.